

SUBSTRATE PROCESSING APPARATUS AND CONTROL METHOD FOR
SUBSTRATE PROCESSING APPARATUS

Abstract

A control method is for controlling a substrate processing apparatus having a plurality of processing units that execute substrate processing by using processing liquid and one or more supply unit(s) that supply heated processing liquid. The control method for controlling the substrate processing apparatus includes an acquiring process, a specifying process and a changing process. The acquiring process acquires a first log information that indicates a status of an execution of the substrate processing of each of the processing units. Specifying process specifies a non-operating interval during which the substrate processing is not executed on the basis of the first log information. The changing process changes processing time of a temperature control process for maintaining temperature of the heated processing liquid in such a manner that the non-operating interval is shortened regarding the supply unit to be used for an unexecuted substrate processing at the non-operating interval.

FIG. 9